

DZ2S068C

Silicon epitaxial planar type

For ESD protection

Bi-directional type

■ Features

- High electrostatic discharge ESD
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: GH

■ Packaging

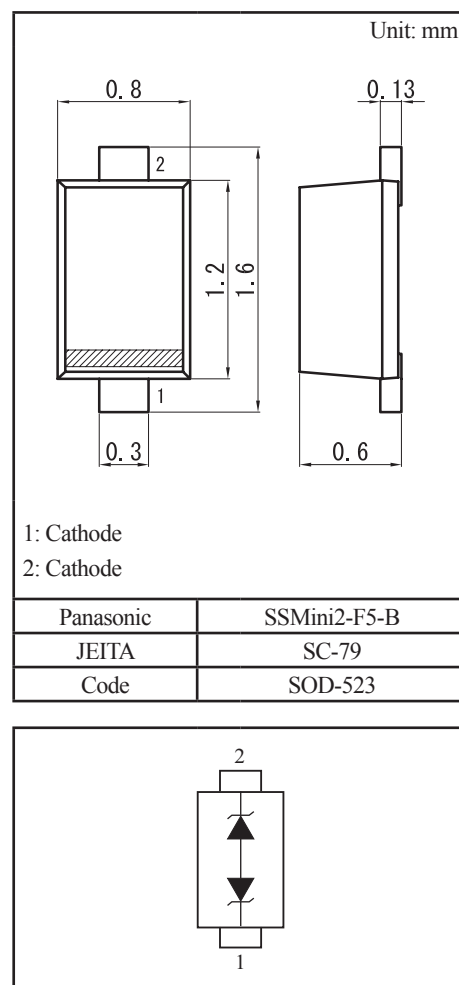
DZ2S068C0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	P_T	150	mW
Electrostatic discharge *2	ESD	± 15	kV
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Mounted on glass epoxy print board. (45 mm × 45 mm × 1 mm)

Solder in (0.8 mm × 0.6 mm)

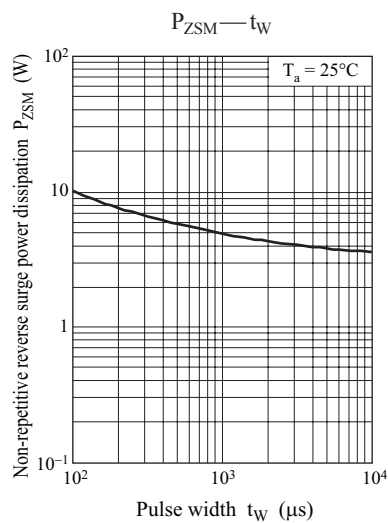
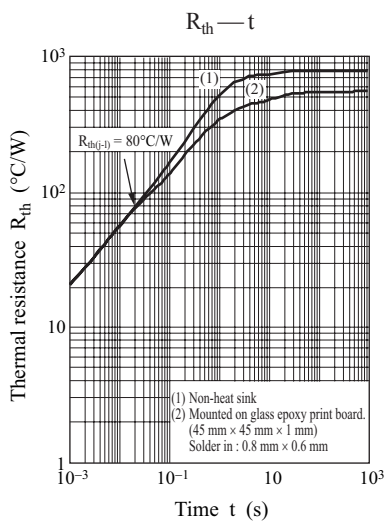
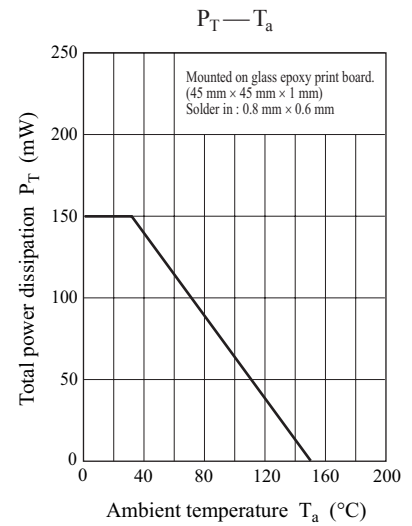
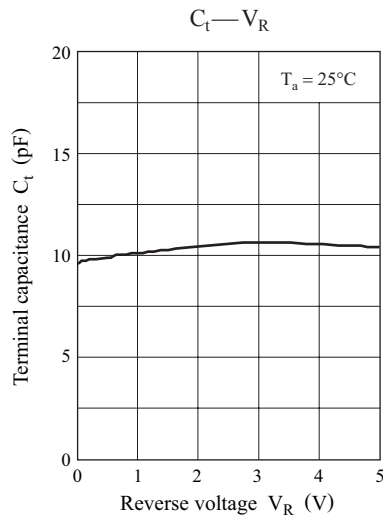
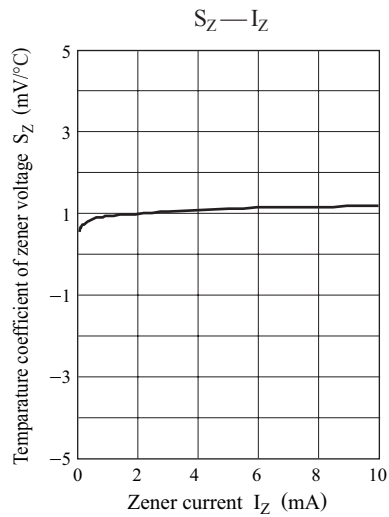
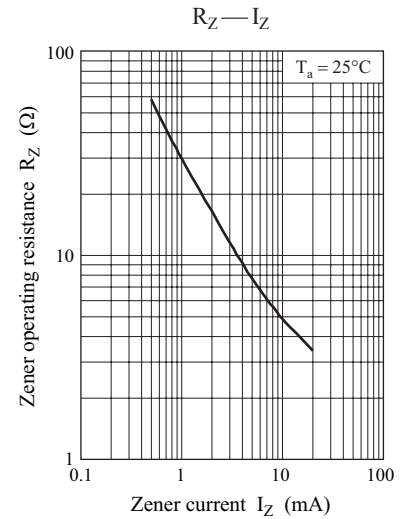
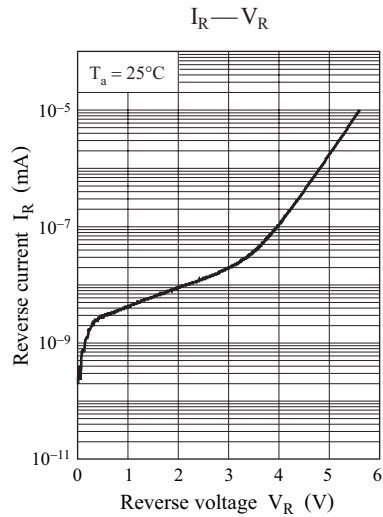
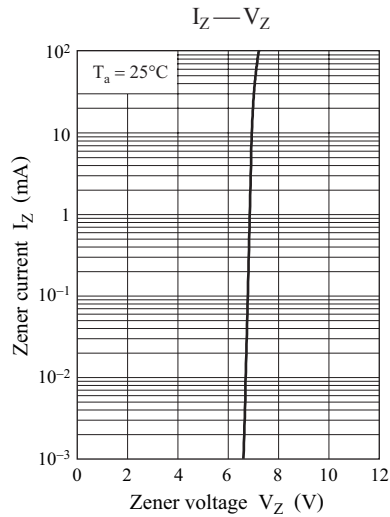
*2: Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *1,2	V_Z	$I_Z = 5 \text{ mA}$	6.50		7.50	V
Zener operating resistance	R_Z	$I_Z = 5 \text{ mA}$			20	Ω
Reverse current	I_R	$V_R = 4.0 \text{ V}$			50	nA
Terminal capacitance	C_t	$V_R = 0 \text{ A}$, $f = 1 \text{ MHz}$		15.0		pF

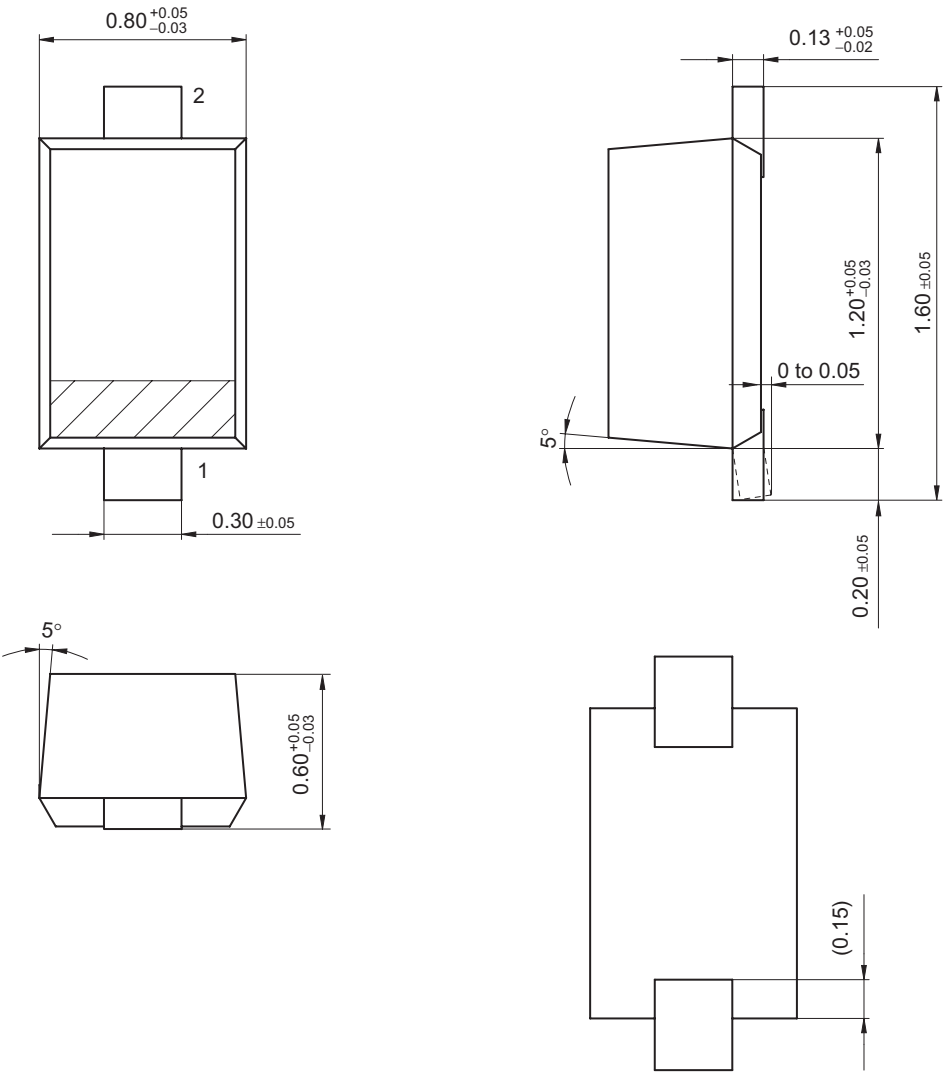
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to $V_Z (25^\circ\text{C})$ *2: V_Z guaranteed 20 ms after current flow.

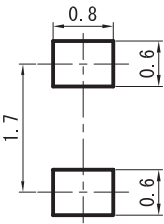


SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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